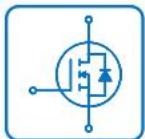




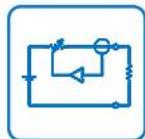
ESD



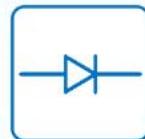
TVS



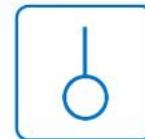
MOS



LDO



Diode



Sensor



DC-DC

Product Specification

▶ Domestic Part Number	IRF9530N
▶ Overseas Part Number	IRF9530N
▶ Equivalent Part Number	IRF9530N

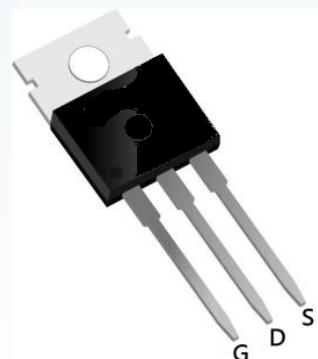


EV is the abbreviation of name EVVO

P-Channel MOSFET

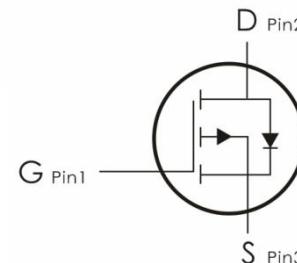
Description:

This P-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.



Features:

- 1) $V_{DS}=-100V, I_D=-20A, R_{DS(on)}<90m\Omega @ V_{GS}=-10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra low $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.

Absolute Maximum Ratings: ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	-100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $T_C=25^\circ C$	-20	A
	Continuous Drain Current- $T_C=100^\circ C$	-14	A
I_{DM}	Pulsed Drain Current ¹	-85	A
P_D	Total Power Dissipation	58	W
E_{AS}	Single Pulsed Avalanche Energy	177	mJ
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	°C

P-Channel MOSFET

Thermal Characteristics:

Symbol	Parameter	Max	Units
$R_{\theta JC}$	Thermal Resistance,Junction to Case	2.15	°C/W
$R_{\theta JA}$	Thermal Resistance Junction-Ambient	62	°C/W

Electrical Characteristics: ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=-250 \mu A$	-100	---	---	V
$I_{DS(on)}$	Zero Gate Voltage Drain Current	$V_{GS}=0V, V_{DS}=-100V$	---	---	-50	μA
I_{GSS}	Gate-Source Leakage Current	$V_{GS}=\pm 20V, V_{DS}=0A$	---	---	± 100	nA
On Characteristics						
$V_{GS(th)}$	GATE-Source Threshold Voltage	$V_{GS}=V_{DS}, I_D=-250 \mu A$	-1.2	-1.7	-2.5	V
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-10A$	---	78	90	$m \Omega$
		$V_{GS}=-4.5V, I_D=-8A$	---	86	110	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS}=-20V, V_{GS}=0V, f=1MHz$	---	3020	---	pF
C_{oss}	Output Capacitance		---	120	---	
C_{rss}	Reverse Transfer Capacitance		---	73	---	
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time ^{2,3}	$V_{DD}=-50V, I_D=-10A,$ $V_{GS}=-10V, R_G=3.3 \Omega$	---	11	---	ns
t_r	Rise Time ^{2,3}		---	27	---	ns
$t_{d(off)}$	Turn-Off Delay Time ^{2,3}		---	78	---	ns
t_f	Fall Time ^{2,3}		---	53	---	ns
Q_g	Total Gate Charge ^{2,3}		---	44	---	nC

P-Channel MOSFET

Q_{gs}	Gate-Source Charge ^{2,3}	$I_D=-20A$	---	9	---	nC
Q_{gd}	Gate-Drain "Miller" Charge ^{2,3}		---	5.5	---	nC
Drain-Source Diode Characteristics						
V_{SD}	Drain Diode Forward Voltage ²	$V_{GS}=0V, I_S=-1A$	---	---	-1.2	V
I_S	Continuous Source Current ^{1,5}	$V_G=V_D=0V$, Force Current	---	---	-20	A
T_{rr}	Reverse Recovery Time	$I_F=-8A$, $dI/dt=-100A/\mu s$, $T_J=25^\circ C$	---	38.7	---	nS
Q_{rr}	Reverse Recovery Charge		---	22.4	---	nC

Notes:

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$
- 3.The EAS data shows Max. rating . The test condition is $V_{DD}=-25V, V_{GS}=-10V, L=0.88mH, I_{AS}=-18.9A$
- 4.The power dissipation is limited by $150^\circ C$ junction temperature
- 5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

Typical Characteristics: ($T_c=25^\circ C$ unless otherwise noted)

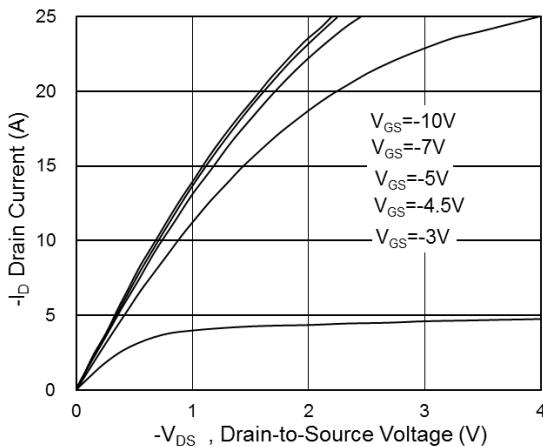


Fig.1 Typical Output Characteristics

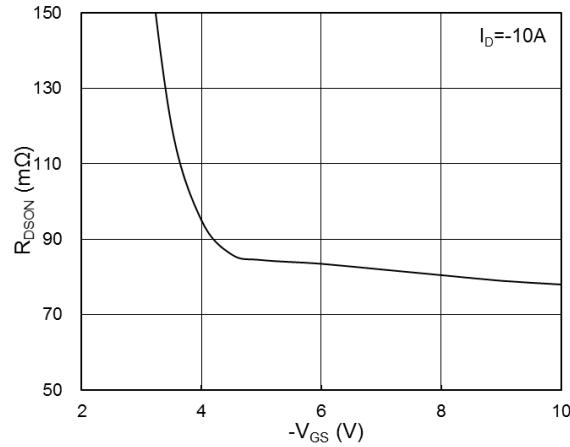


Fig.2 On-Resistance vs G-S Voltage

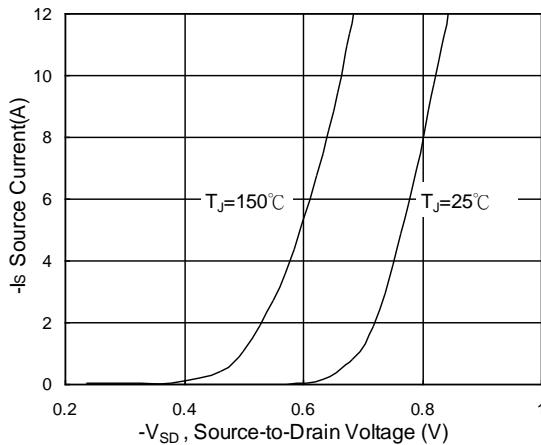


Fig.3 Typical S-D Diode Forward Voltage

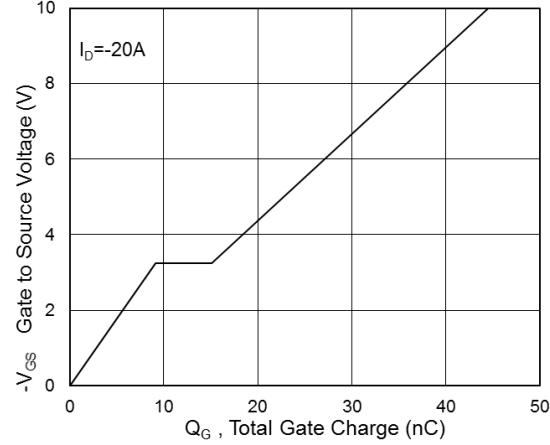


Fig.4 Gate-Charge Characteristics

P-Channel MOSFET

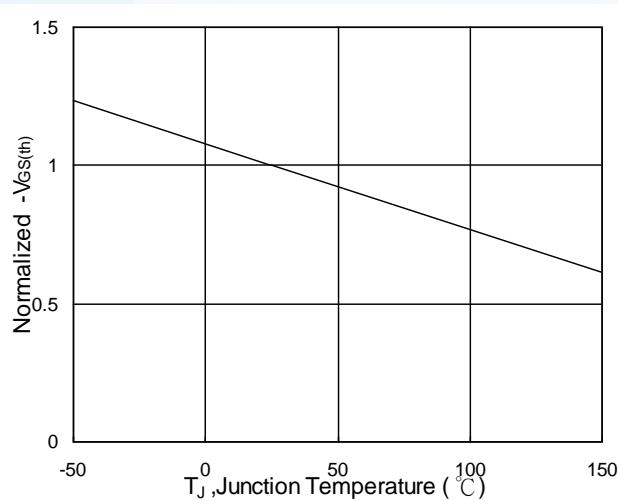


Fig.5 Normalized $V_{GS(th)}$ vs T_J

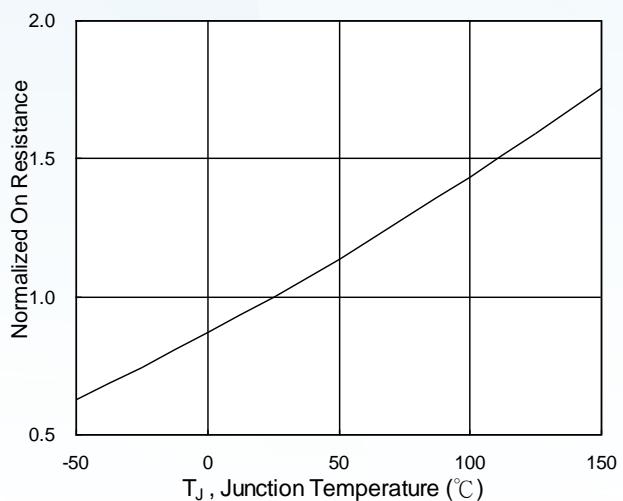


Fig.6 Normalized $R_{DS(on)}$ vs T_J

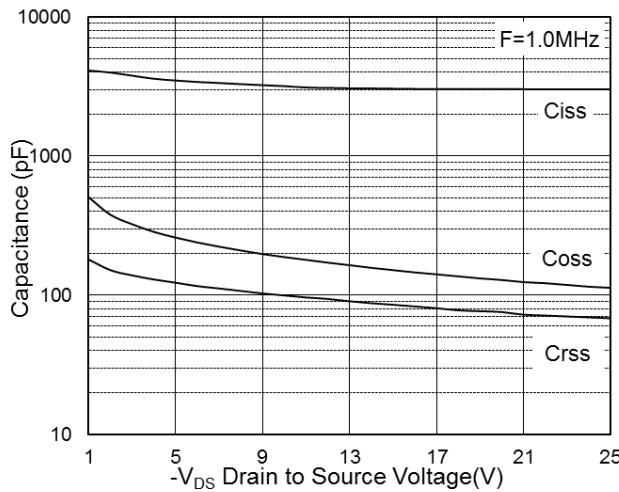


Fig.7 Capacitance

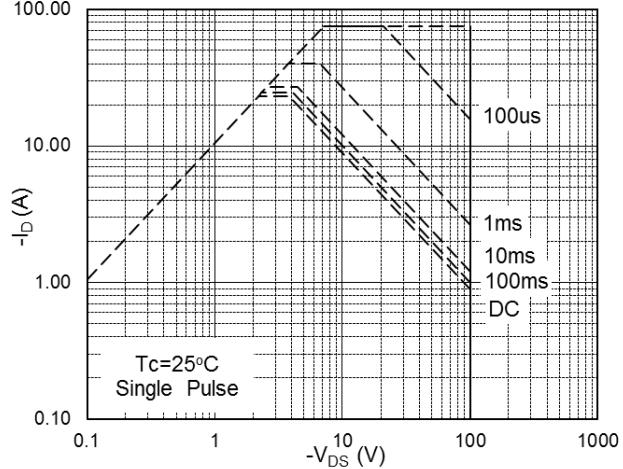


Fig.8 Safe Operating Area

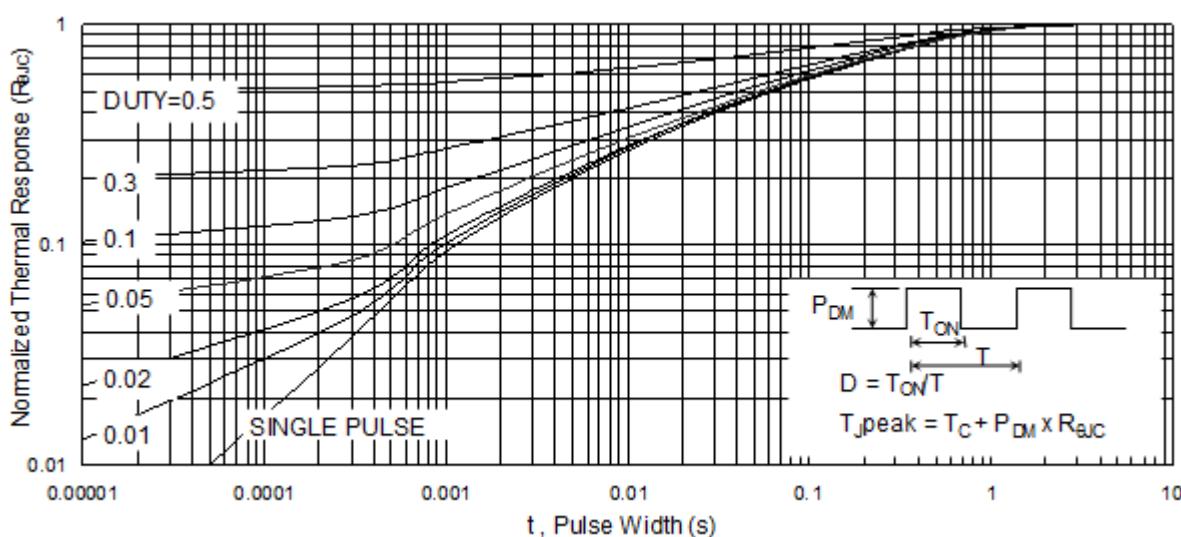


Fig.9 Normalized Maximum Transient Thermal Impedance

P-Channel MOSFET

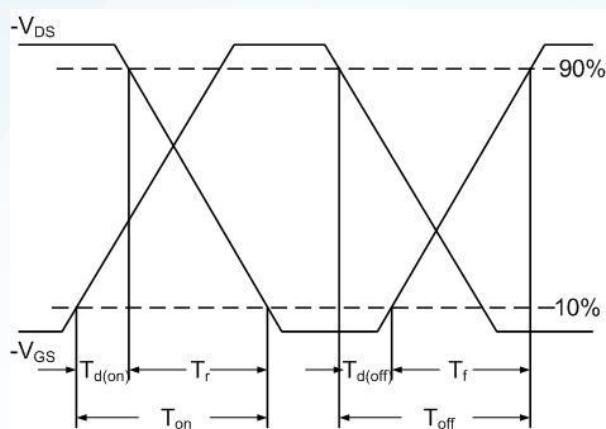


Fig.10 Switching Time Waveform

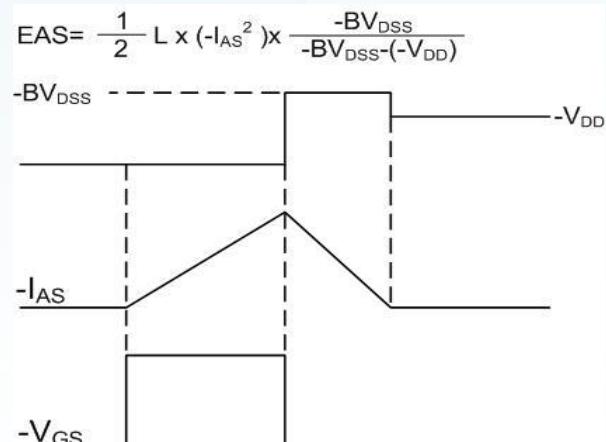
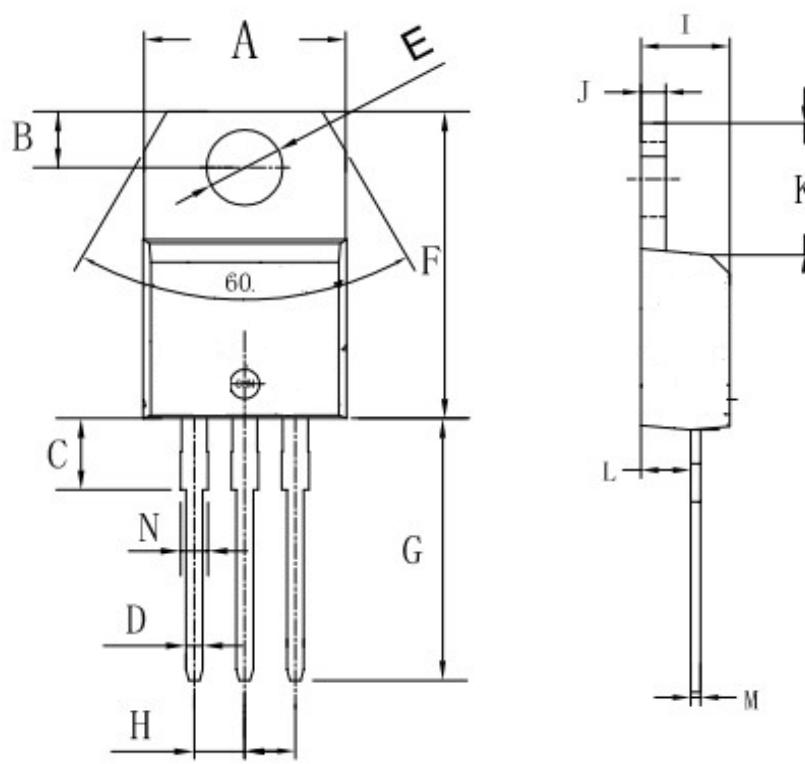


Fig.11 Unclamped Inductive Waveform

P-Channel MOSFET

Package Dimensions



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	9.8	10.4	0.385	0.409
B	2.65	3.1	0.104	0.122
C	2.8	4.2	0.110	0.165
D	0.7	0.92	0.027	0.036
E	3.75	3.95	0.147	0.155
F	14.8	16.1	0.582	0.633
G	13.05	13.6	0.513	0.535
H	2.4	2.7	0.094	0.106
I	4.38	4.61	0.172	0.181
J	1.15	1.36	0.045	0.053
K	5.85	6.82	0.230	0.268
L	2.35	2.75	0.092	0.108
M	0.35	0.65	0.013	0.025
N	1.18	1.42	0.046	0.055

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